

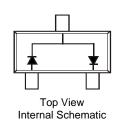
DUAL SURFACE MOUNT SWITCHING DIODE

Features

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automated Insertion
- For General Purpose Switching Applications
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Notes 3 & 4)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound (Note 2). UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Weight: 0.008 grams (approximate)



Top View

SOT23

Ordering Information (Note 5)

Part Number	Qualification	Case	Packaging
BAV99-7-F	Commercial	SOT23	3,000/Tape & Reel
BAV99-13-F	Commercial	SOT23	10,000/Tape & Reel
BAV99Q-7-F	Automotive	SOT23	3,000/Tape & Reel
BAV99Q-13-F	Automotive	SOT23	10,000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

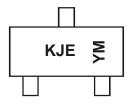
2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

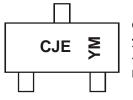
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Product manufactured with Date Code 9W (week 39, 2009) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 9W are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.

5. For packaging details, go to our website at http://www.diodes.com.

Marking Information





 $\begin{array}{l} C = CAT \mbox{ (Chengdu Assembly / Test site)} \\ JE = Product Type Marking Code \\ YM = Date Code Marking \\ Y = Year \mbox{ (ex: } Z = 2012) \\ M = Month \mbox{ (ex: } 9 = September) \end{array}$

Date Code Key

Year	1998	1999		2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017
Code	J	K		Т	U	V	W	Х	Y	Z	А	В	С	D	E
Month	Jan	Feb)	Mar	Apr	Мау	Ju	n	Jul	Aug	Sep	Oc	t	Nov	Dec
Code										-	-	_			-



Maximum Ratings $@T_A = 25$ °C unless otherwise specified

Characteristic		Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage		V _{RM}	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _{RWM} V _R	75	V
RMS Reverse Voltage		V _{R(RMS)}	53	V
Forward Continuous Current (Note 6)		I _{FM}	300	mA
Non-Repetitive Peak Forward Surge Current	@ t = 1.0μs @ t = 1.0s	I _{FSM}	2.0 1.0	A

Thermal Characteristics

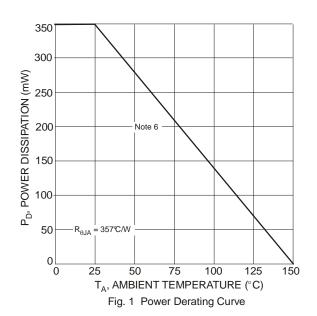
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	PD	350	mW
Thermal Resistance Junction to Ambient Air (Note 6)	$R_{ heta}$ JA	357	°C/W
Operating and Storage Temperature Range	TJ, T _{STG}	-65 to +150	O°

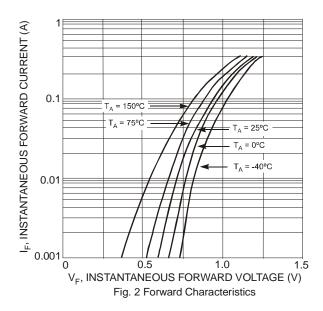
Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V _{(BR)R}	75	_	V	I _R = 2.5μA
Forward Voltage	VF		0.715 0.855 1.0 1.25	V	$I_{F} = 1.0mA$ $I_{F} = 10mA$ $I_{F} = 50mA$ $I_{F} = 150mA$
Reverse Current (Note 7)	I _R	_	2.5 50 30 25	μΑ μΑ μΑ nA	$V_R = 75V$ $V_R = 75V$, $T_J = 150^{\circ}C$ $V_R = 25V$, $T_J = 150^{\circ}C$ $V_R = 20V$
Total Capacitance	CT	_	2.0	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{rr}		4.0	ns	$I_F = I_R = 10 \text{mA},$ $I_{rr} = 0.1 \text{ x } I_R, R_L = 100 \Omega$

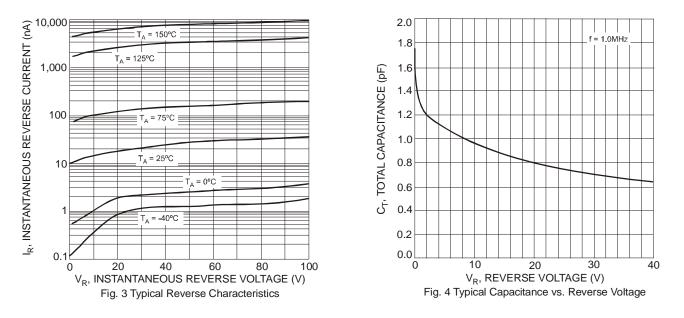
Notes:

Part mounted on Polymide PC board with pad dimensions 1.13mm x 1.27mm.
Short duration pulse test used to minimize self-heating effect.

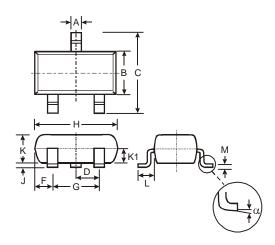






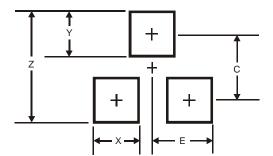


Package Outline Dimensions



SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
С	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Н	2.80	3.00	2.90				
J	0.013	0.10	0.05				
Κ	0.903	1.10	1.00				
K1	-	-	0.400				
L	0.45	0.61	0.55				
М	0.085	0.18	0.11				
α	0°	8°	-				
All	Dimens	ions in	mm				

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.9
Х	0.8
Y	0.9
С	2.0
E	1.35



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